



Silicon sensors characterisation for the CMS Endcap Calorimeter Upgrade

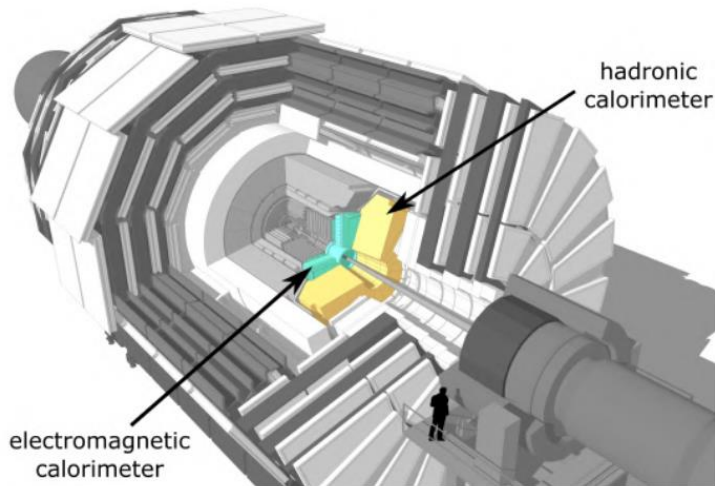
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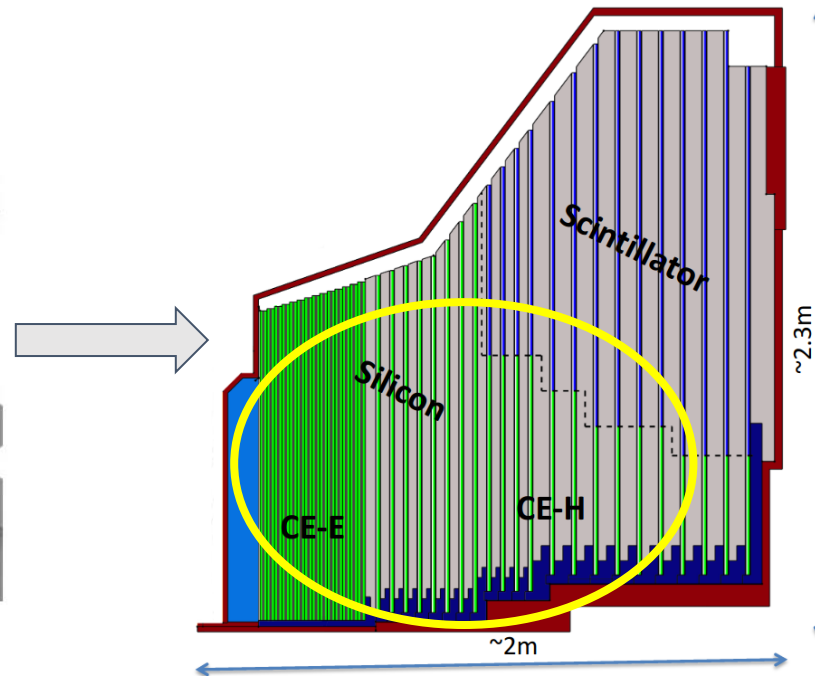
Wuppertal

17.07 - 28.07.2023

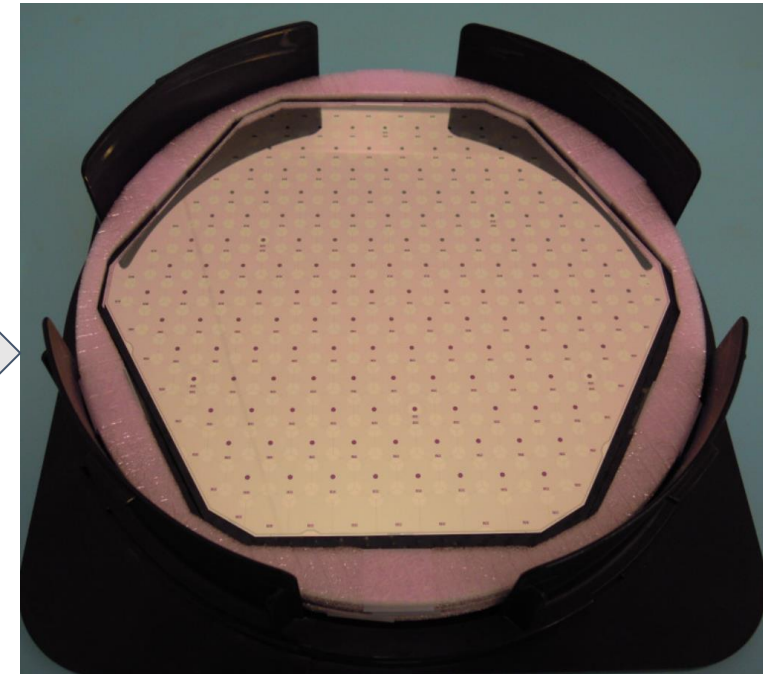
Current CMS Endcap Calorimeter ...



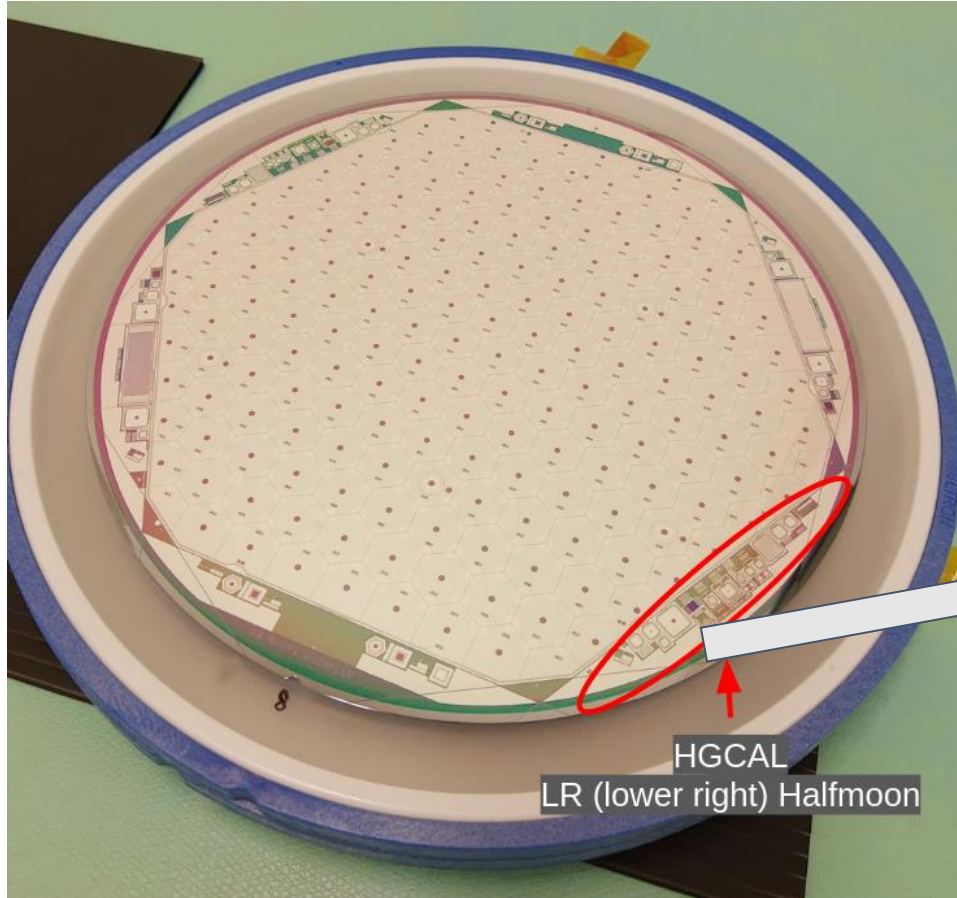
... will be replaced by the High Granularity Calorimeter (HGCal) ...



... and in the high radiation region will be based on 8-inch Si sensors



Full wafers and small “test structures” are characterised

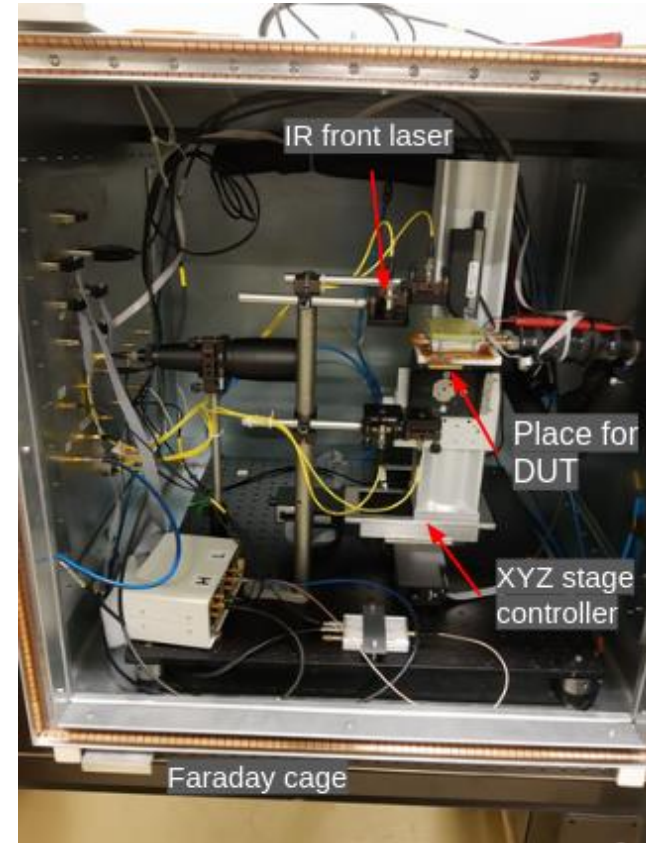
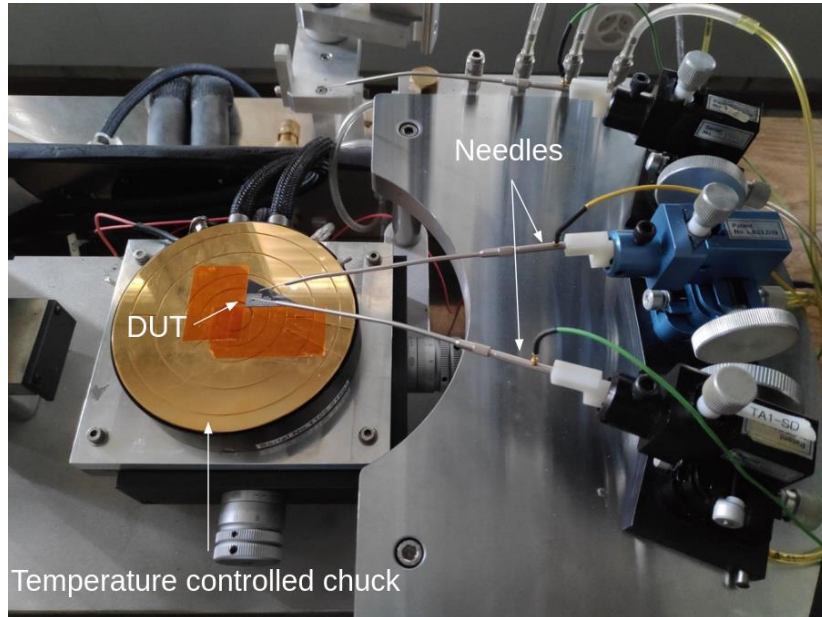


Example test structure diode

Full wafer hexagonal sensor on circular wafer containing various test structures

Three sensor thicknesses: 300 μm , 200 μm , 120 μm

Neutron-irradiated diodes tested in two setups



Leakage current (IV)
Capacitance (CV) -> full depletion voltage

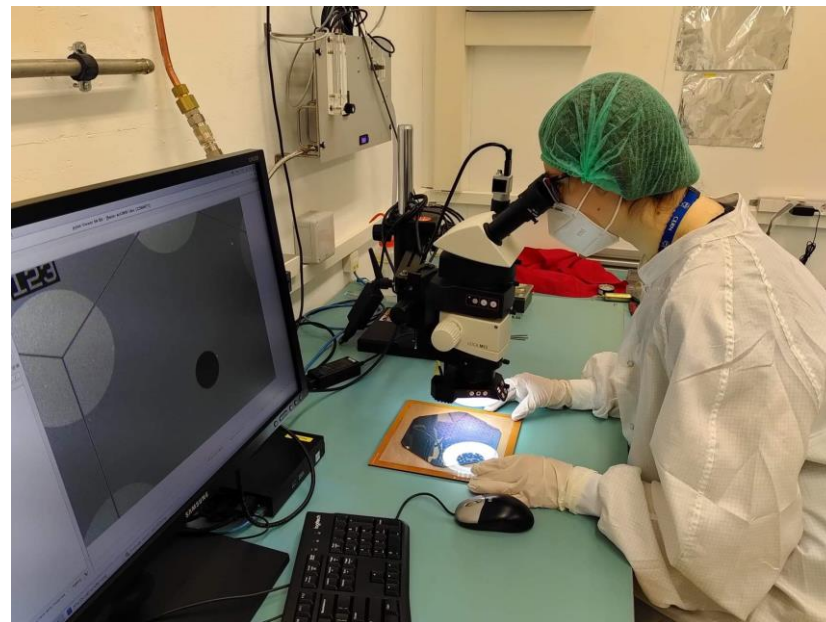
Charge collection studies -> efficiency

Diodes are annealed in multiple steps and remeasured

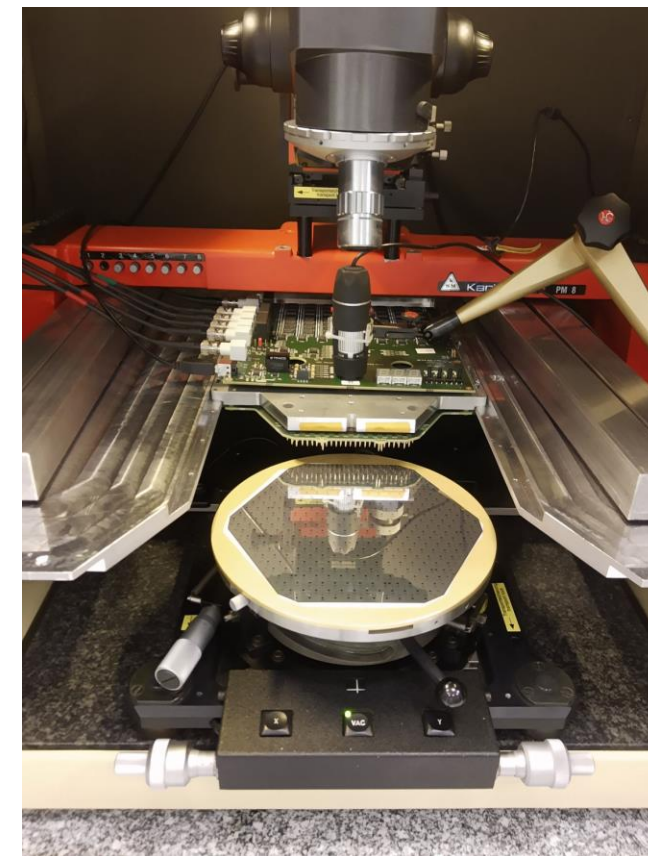
Full wafers are electrically characterized in cleanroom conditions



Handling the sensor



Visual inspection of the DUT



DUT placed inside the setup, before contacting

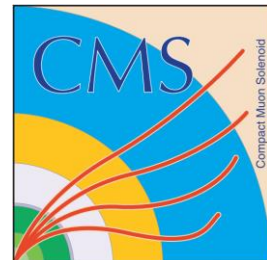
Custom-made system enables automatic testing of the full wafer



Take-home messages



- Radiation-tolerance study of full wafer 8-inch sensors as well as small test structure diodes
- Tests include electrical characterization (IV,CV) and charge collection measurements
- Based on these results, sensors of certain properties (e.g. thickness) will be chosen for respective parts of HGCALE
- Silicon sensors will cover an area of $\sim 620 \text{ m}^2$ of HGCALE ($\sim 30\,000$ 8-inch sensors)



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